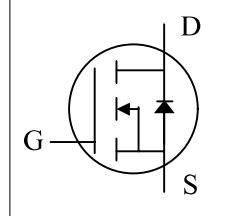


AP0903G

N-Channel Power MOSFET

- ▼ Simple Drive Requirement
- ▼ Good Thermal Dissipation
- ▼ Low On-resistance
- ▼ RoHS Compliant & Halogen-Free

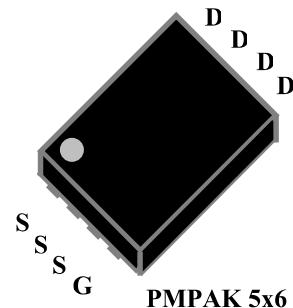


BV_{DSS}	30V
$R_{DS(ON)}$	10mΩ
I_D	20A

Description

Advanced Power MOSFETs from AP provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The PMPAK® 5 x 6 package is special for DC-DC converters application and lower 1.0mm profile with backside heat sink.



Absolute Maximum Ratings@ $T_j=25^\circ\text{C}$ (unless otherwise specified)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	30	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D @ T_A = 25^\circ\text{C}$	Drain Current ³ , $V_{GS} @ 10\text{V}$	20	A
$I_D @ T_A = 70^\circ\text{C}$	Drain Current ³ , $V_{GS} @ 10\text{V}$	15	A
I_{DM}	Pulsed Drain Current ¹	44	A
$P_D @ T_A = 25^\circ\text{C}$	Total Power Dissipation	25	W
T_{STG}	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Value	Units
R_{thj-a}	Maximum Thermal Resistance, Junction-ambient ³	35	°C/W

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Electrical Characteristics@ $T_j=25^\circ\text{C}$ (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	30	-	-	V
$R_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance ²	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=10\text{A}$	-	-	10	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=8\text{A}$	-	-	16	$\text{m}\Omega$
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	1	-	3	V
g_{fs}	Forward Transconductance	$V_{\text{DS}}=10\text{V}, I_{\text{D}}=10\text{A}$	-	24	-	S
I_{DSS}	Drain-Source Leakage Current	$V_{\text{DS}}=30\text{V}, V_{\text{GS}}=0\text{V}$	-	-	10	μA
	Drain-Source Leakage Current ($T_j=70^\circ\text{C}$)	$V_{\text{DS}}=24\text{V}, V_{\text{GS}}=0\text{V}$	-	-	250	μA
I_{GSS}	Gate-Source Leakage	$V_{\text{GS}}=+20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	± 100	nA
Q_g	Total Gate Charge ²	$I_{\text{D}}=10\text{A}$	-	8.7	14	nC
Q_{gs}	Gate-Source Charge		-	1.7	-	nC
Q_{gd}	Gate-Drain ("Miller") Charge		-	5	-	nC
$t_{\text{d}(\text{on})}$	Turn-on Delay Time ²	$V_{\text{DS}}=15\text{V}$	-	10	-	ns
t_r	Rise Time	$I_{\text{D}}=1\text{A}$	-	7	-	ns
$t_{\text{d}(\text{off})}$	Turn-off Delay Time	$R_{\text{G}}=6\Omega$	-	24	-	ns
t_f	Fall Time	$V_{\text{GS}}=10\text{V}$	-	8	-	ns
C_{iss}	Input Capacitance	$V_{\text{GS}}=0\text{V}$	-	635	1010	pF
C_{oss}	Output Capacitance	$V_{\text{DS}}=25\text{V}$	-	215	-	pF
C_{rss}	Reverse Transfer Capacitance	$f=1.0\text{MHz}$	-	125	-	pF
R_g	Gate Resistance	$f=1.0\text{MHz}$	-	1.8	-	Ω

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V_{SD}	Forward On Voltage ²	$I_{\text{S}}=2.9\text{A}, V_{\text{GS}}=0\text{V}$	-	-	1.2	V
t_{rr}	Reverse Recovery Time ²	$I_{\text{S}}=10\text{A}, V_{\text{GS}}=0\text{V},$ $dI/dt=100\text{A}/\mu\text{s}$	-	27	-	ns
Q_{rr}	Reverse Recovery Charge		-	20	-	nC

Notes:

- 1.Pulse width limited by Max. junction temperature.
- 2.Pulse test
- 3.Surface mounted on 1 in² copper pad of FR4 board, t \leq 10sec

THIS PRODUCT IS SENSITIVE TO ELECTROSTATIC DISCHARGE, PLEASE HANDLE WITH CAUTION.

USE OF THIS PRODUCT AS A CRITICAL COMPONENT IN LIFE SUPPORT OR OTHER SIMILAR SYSTEMS IS NOT AUTHORIZED.

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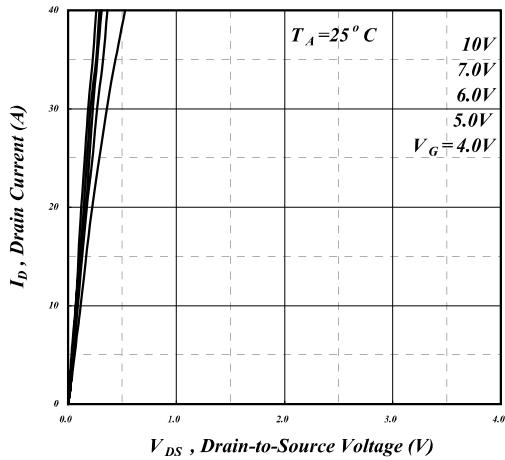


Fig 1. Typical Output Characteristics

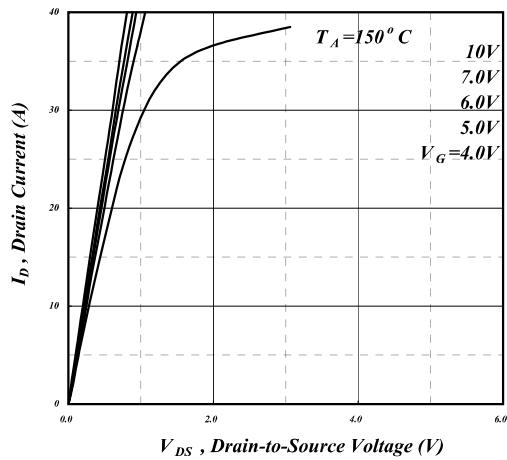


Fig 2. Typical Output Characteristics

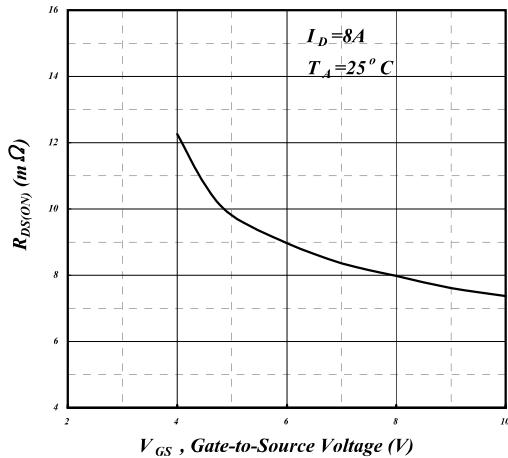


Fig 3. On-Resistance v.s. Gate Voltage

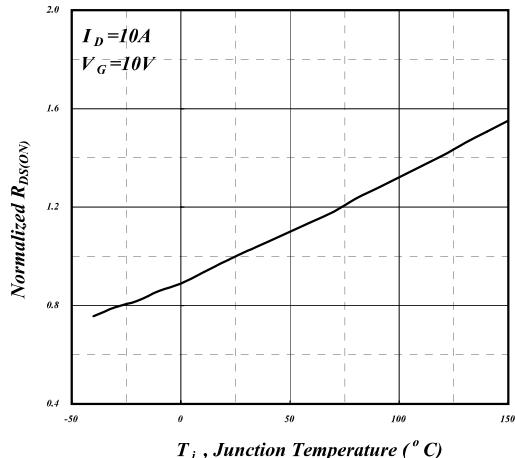


Fig 4. Normalized On-Resistance
v.s. Junction Temperature

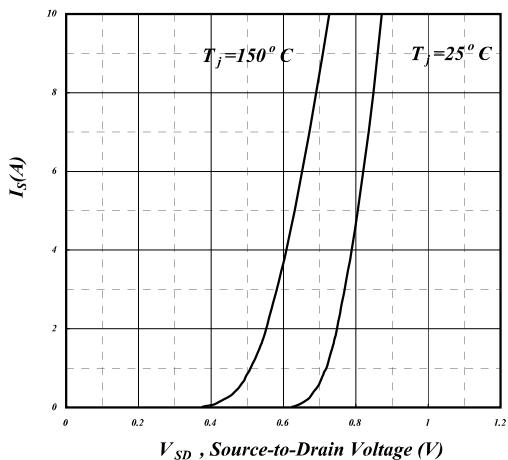


Fig 5. Forward Characteristic of
Reverse Diode

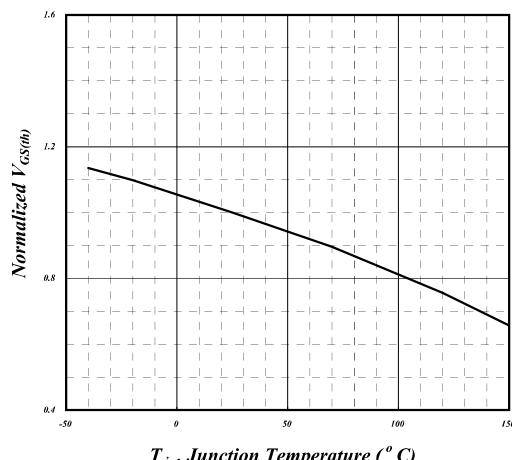


Fig 6. Gate Threshold Voltage v.s.
Junction Temperature

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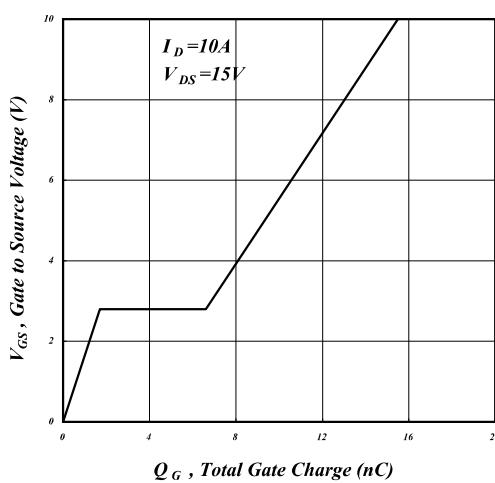


Fig 7. Gate Charge Characteristics

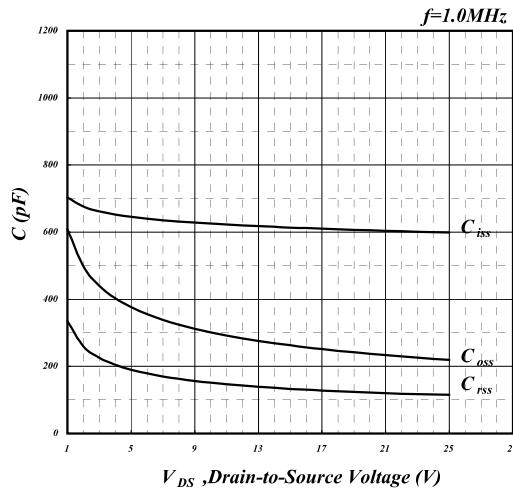


Fig 8. Typical Capacitance Characteristics

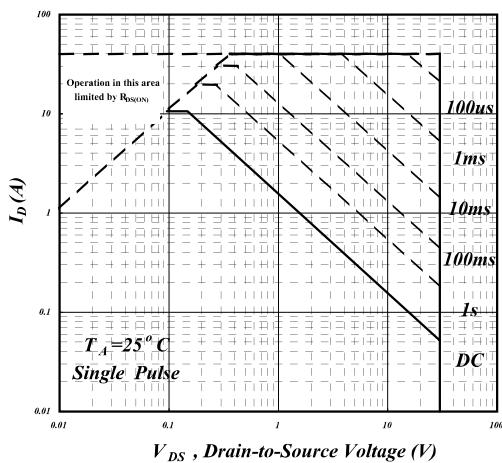


Fig 9. Maximum Safe Operating Area

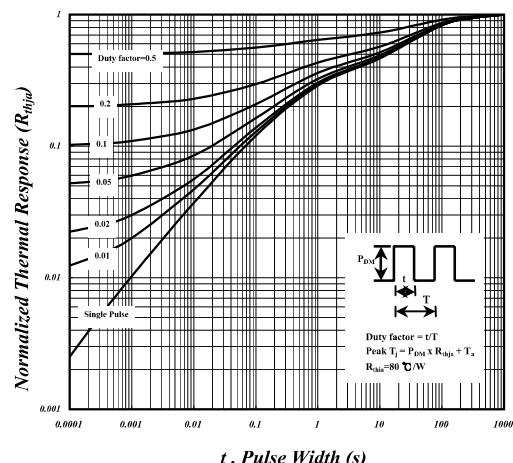


Fig 10. Effective Transient Thermal Impedance

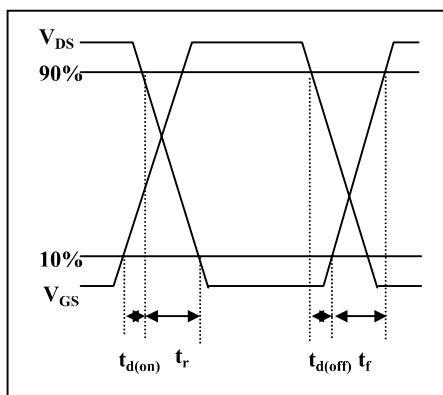


Fig 11. Switching Time Waveform

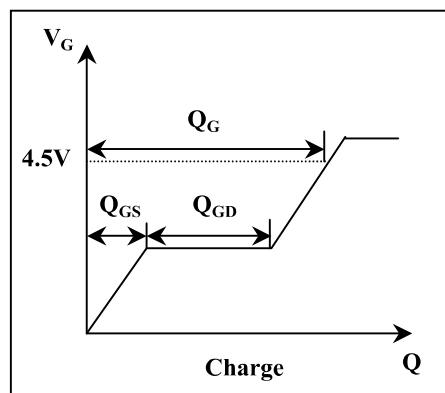
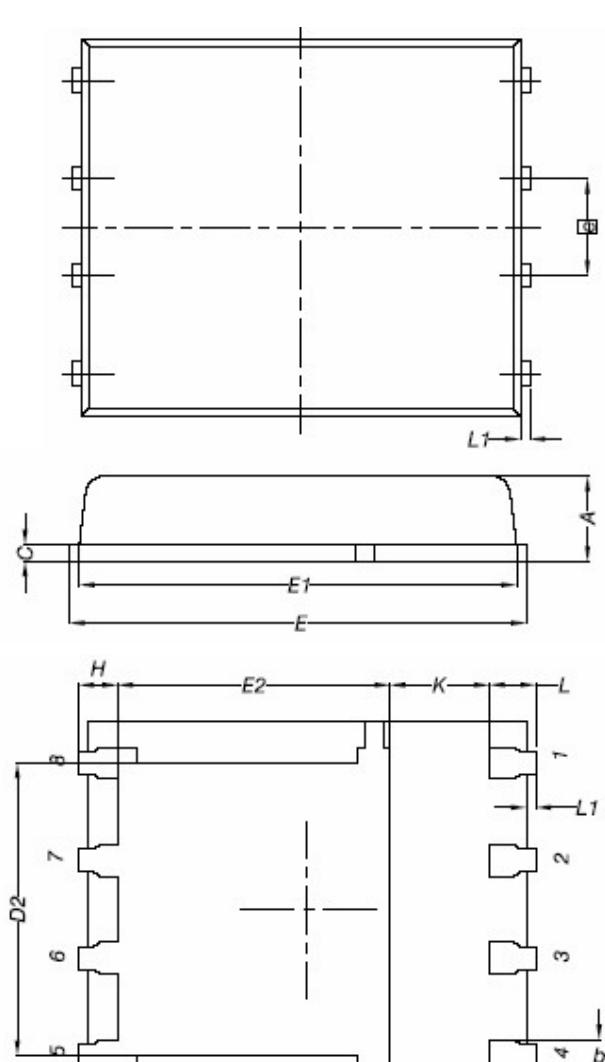


Fig 12. Gate Charge Waveform

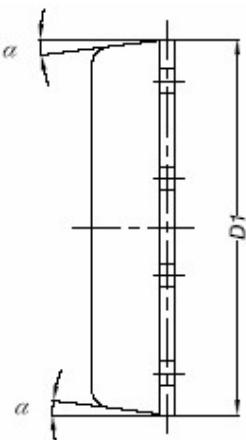
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N-Channel Power MOSFET

Package Outline : PMPAK 5x6



BACKSIDE VIEW



SYMBOLS	Millimeters		
	MIN	NOM	MAX
A	0.90	1.00	1.10
b	0.33	0.41	0.51
C	0.20	-	-
D1	4.80	4.90	5.10
D2	-	-	4.20
E	5.90	6.00	6.10
E1 (Reference)	5.70	5.75	5.80
E2 (Reference)	3.38	3.58	3.78
e	1.27 BSC		
H	-	-	0.62
K (Reference)	0.70	-	-
L	0.51	0.61	0.71
L1	-	-	0.20
α (Reference)	0°	-	12°

1. All Dimension Are In Millimeters.

2. Dimension Does Not Include Mold Protrusions.